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Electronic Version v1.1

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Title of Invention	Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking		
Application Number :	10/050507		
Date :	2002-01-16		
First Named Applicant:	Lee Teck		
Confirmation Number:	7687		
Attorney Docket Number:	MTI-31607		
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Documents being submitted:	Files
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